

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **06/14/2022**

Details for "LMS017MRX/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LMS017MRX/NOPB	SN	Level-3-260C-168 HR	Texas Instruments Electronics	DDA 8	4.9 x 3.9 x 1.75	85.2

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.110247	98.733667	987337	0.129454	1295
Nickel and Its Alloys	Nickel	7440-02-0	0.000001	0.000896	9	0.000001	0
Not Categorized	Proprietary Materials		0.000012	0.010747	107	0.000014	0
Precious Metals	Gold	7440-57-5	0.000024	0.021494	215	0.000028	0
Precious Metals	Palladium	7440-05-3	0.001374	1.23051	12305	0.001613	16
Precious Metals	Silver	7440-22-4	0.000003	0.002687	27	0.000004	0
Sub-Total			0.111661	100	1000000	0.131114	1311
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.583174	75.000032	750000	0.684774	6848
Thermoplastics	Epoxy	85954-11-6	0.194391	24.999968	250000	0.228258	2283
Sub-Total			0.777565	100	1000000	0.913032	9130
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	22.445192	96.58	965800	26.355568	263556
Copper and Its Alloys	Iron	7439-89-6	0.55776	2.4	24000	0.654932	6549
Copper and Its Alloys	Phosphorus	7723-14-0	0.006972	0.03	300	0.008187	82
Precious Metals	Silver	7440-22-4	0.202188	0.87	8700	0.237413	2374
Zinc and Its Alloys	Zinc	7440-66-6	0.027888	0.12	1200	0.032747	327
Sub-Total			23.24	100	1000000	27.288847	272888
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.49	100	1000000	1.749586	17496
Sub-Total			1.49	100	1000000	1.749586	17496
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	49.251025	89.000001	890000	57.831483	578315
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	1.660147	3	30000	1.949376	19494
Thermoplastics	Epoxy	85954-11-6	4.427058	7.999999	80000	5.198335	51983
Sub-Total			55.33823	100	1000000	64.979194	649792
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	4.205542	100	1000000	4.938227	49382
Sub-Total			4.205542	100	1000000	4.938227	49382
Total			85.162998			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.